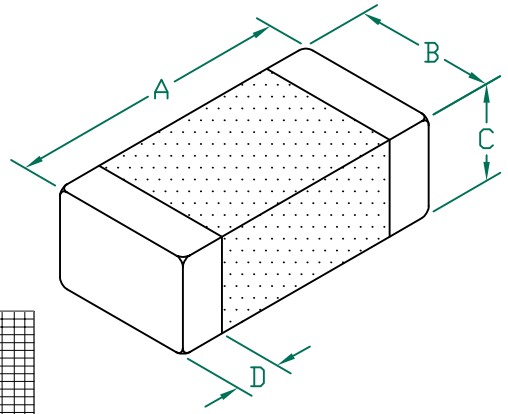
# LF1206E152R-10

**UNCONTROLLED DOCUMENT**

## PHYSICAL DIMENSIONS:

| | | | |
|---|---|---|---|
| A | 3.20 [.126] | ± | 0.20 [.008] |
| B | 1.60 [.063] | ± | 0.20 [.008] |
| C | 1.10 [.043] | ± | 0.20 [.008] |
| D | 0.51 [.020] | ± | 0.25 [.010] |



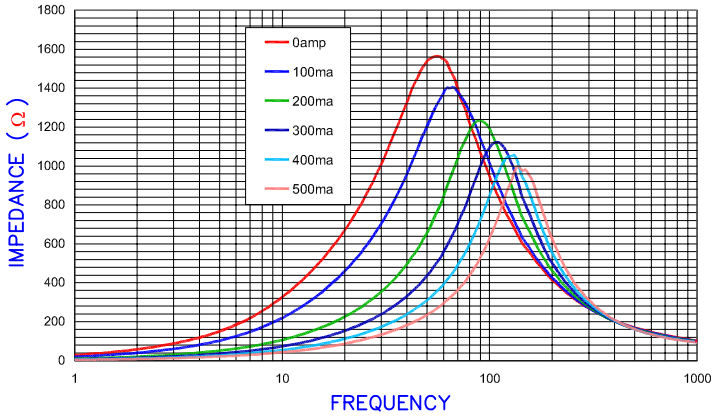

| ELECTRICAL CHARACTERISTICS: | | | |
|---|---|---|---|
| Z @ 50MHz ( Ω ) | | DCR ( Ω ) | Rated Current |
| Nominal | 1500 | | |
| Minimum | 1125 | | |
| Maximum | 1875 | 0.300 | 500 mA |

NOTES: UNLESS OTHERWISE SPECIFIED

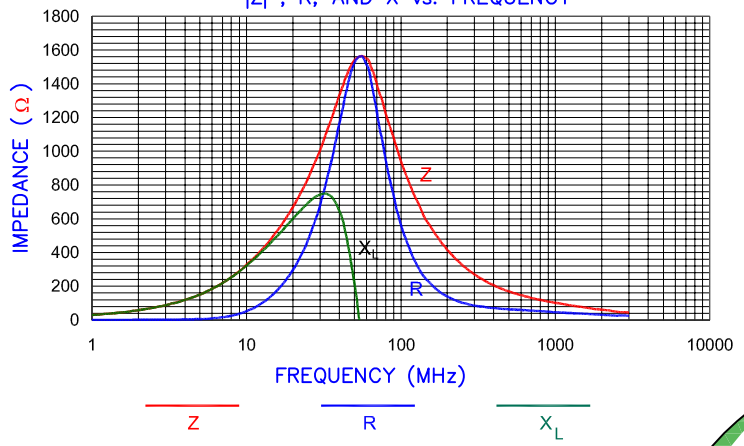
1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 3000 PCS/REEL, EMBOSSED PLASTIC TAPE.
2. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
3. TERMINATION FINISH IS 100% TIN.
4. OPERATING TEMPERATURE: −40°C~+125°C. (INCLUDING SELF−HEATING)

Pb

Z vs FREQUENCY
IMPEDANCE UNDER DC BIAS




|Z| , R, AND X vs. FREQUENCY

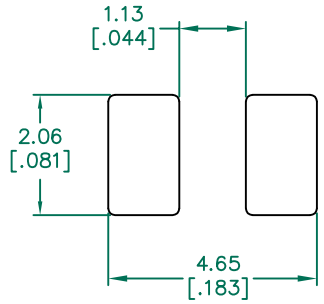



Z R $X_L$

RoHS 2002/95/EC

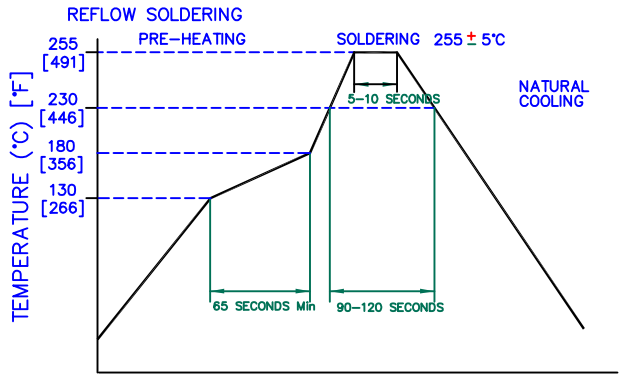
AGILENT E4991A RF Impedance/Material Analyzer
HP 16194A Test Fixture REF. 4405

LAND PATTERNS FOR REFLOW SOLDERING




(For wave soldering, add 0.762 [0.030] to this dimension)

RECOMMENDED SOLDERING CONDITIONS




| REV | DESCRIPTION | DATE | INT |
|---|---|---|---|
| | | | |
| | | | |
| D | UPDATE LAIRD LOGO AND NOTES 4 | 08/05/13 | QU |
| C | ADD OPERATING TEMPERATURE<br>UPDATE Z IMPEDANCE AT 50MHz AND REFLOW | 02/19/13 | QU |
| B | UPDATE COMPANY LOGO & ROHS SYMBOL | 07/08/08 | JRK |
| A | ORIGINAL DRAFT | 09/13/06 | JRK |

DIMENSIONS ARE IN mm [INCHES].



Laird

| PROJECT/PART NUMBER: | REV | PART TYPE: | DRAWN BY: |
|---|---|---|---|
| LF1206E152R−10 | D | CO−FIRE | JRK |

| DATE: | SCALE: | SHEET: |
|---|---|---|
| 09/13/06 | NTS | 2 of 2 |

CAD # LF1206E152R−10−D TOOL # −